

Amendment

Applicant: Andreas Meckes et al.

Serial No.: 10/723,998

Filed: November 26, 2003

Docket No.: 2002P15009US (I431.101.101)

Title: ELECTRONIC COMPONENT AND METHOD FOR ITS PRODUCTION

Amendments to the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-6. (Cancelled)

7. (Original) An electronic component comprising a semiconductor die, the semiconductor die comprising:

a semiconductor substrate,
an active top side on the semiconductor substrate,
an active surface area on the active top side,
contact connecting areas electrically connected to the active surface area,
a package comprising a package-forming plastic layer which covers the substrate leaving the contact connecting areas exposed, and

a self-supporting electrically conductive cover layer which is arranged above the active surface area and which is supported on through lines to the active top side and forms a hollow space between the active surface area and cover layer,

wherein the height of the hollow space corresponds to the thickness of an insulation layer, photoresist layer or metal layer for a semiconductor wafer.

8. (Original) The electronic component as claimed in claim 7, wherein the cover layer has a thickness which corresponds to a thickness of conductor tracks on a semiconductor wafer.

9. (Original) The electronic component as claimed in claim 7, wherein the contact connecting areas are arranged outside the active surface area and comprise external contacts of the electronic component.

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10. (Original) The electronic component as claimed in claim 7, wherein the package-forming plastic layer covers the cover layer, leaving the contact connecting areas exposed, and seals the hollow space on the side between the through lines.

11. (Original) The electronic component as claimed in claim 7, further comprising a first plastic layer on which a rewiring pattern with rewiring lines is arranged which lead from the contact connecting areas to external contact areas, external contacts being arranged on the external contact areas, and a second plastic layer is arranged on the first plastic layer, leaving the external contacts exposed and embedding the rewiring pattern.

12. (Original) The electronic component as claimed in claim 11, wherein the through lines are arranged regularly distributed around the circumference of the cover layer.

13. (Original) The electronic component as claimed in claim 7, wherein the through lines are arranged regularly distributed around the circumference of the cover layer.

14. (Original) The electronic component as claimed in claim 7, wherein the cover layer comprises a metal or a semiconductor material.

15. (Currently Amended) The electronic component as claimed in claim 14, wherein the ~~metal or semiconductor material is cover layer~~ comprises heavily doped polycrystalline silicon.

16. (Original) The electronic component as claimed in claim 7, wherein the semiconductor die contains a filter circuit, the filter circuit being implemented using film bulk acoustic resonators.

17. (Original) A semiconductor wafer comprising electronic components arranged in rows and columns, each electronic component comprising a semiconductor die, the semiconductor die comprising:

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a semiconductor substrate,
an active top side on the semiconductor substrate,
an active surface area on the active top side,
contact connecting areas electrically connected to the active surface area,
a package comprising a package-forming plastic layer which covers the substrate leaving the contact connecting areas exposed, and
a self-supporting electrically conductive cover layer which is arranged above the active surface area and which is supported on through lines to the active top side and forms a hollow space between the active surface area and cover layer,
wherein the height of the hollow space corresponds to the thickness of an insulation layer, photoresist layer or metal layer for a semiconductor wafer.

18. (Original) A semiconductor wafer as claimed in claim 17 further comprising conductor tracks, the cover layer having a thickness which corresponds to the thickness of the conductor tracks.

19. (Original) A semiconductor wafer as claimed in claim 17, wherein the contact connecting areas are arranged outside the active surface area and comprise external contacts of the electronic component.

20. (Original) A semiconductor wafer as claimed in claim 17, further comprising a first plastic layer on which a rewiring pattern with rewiring lines is arranged which lead from the contact connecting areas to external contact areas, external contacts being arranged on the external contact areas, and a second plastic layer is arranged on the first plastic layer, leaving the external contacts exposed and embedding the rewiring pattern.